



Material Content Data Sheet



Sales Product Name		TDA4862G GEG		Issued		19. July 2018		
MA#		MA001039460						
Package		PG-DSO-8-41		Weight*		81.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.859	3.52	3.52	35243	35243
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.673	0.83		8297	
wire	non noble metal	copper	7440-50-8	27.330	33.69	34.57	336888	345704
	noble metal	gold	7440-57-5	0.107	0.13	0.13	1321	1321
	encapsulation	organic material	carbon black	1333-86-4	0.143	0.18		1764
encapsulation	plastics	epoxy resin	-	4.627	5.70		57040	
	inorganic material	silicondioxide	60676-86-0	42.934	52.93	58.81	529233	588037
leadfinish	non noble metal	tin	7440-31-5	0.824	1.02	1.02	10157	10157
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1104	1104
glue	plastics	acrylic resin	-	0.299	0.37		3687	
	noble metal	silver	7440-22-4	1.196	1.47	1.84	14747	18434
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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